Atty Dkt. No.: 046602.00359

AMENDMENTS TO THE CLAIMS:

Amendment Under 37 CFR §1.116

U.S. Patent Appln. No.: 09/847,111

1. (Currently Amended) A measuring system of a gas-stream environment, said measuring system of the gas stream environment comprising:

a stage, said stage <u>locating located</u> on a transport apparatus and a wafer <u>placing placed</u> on said stage;

a datum platen, said datum platen <u>locating located</u> on said transport apparatus and on a side of said stage to place for placement of a datum slice, wherein said datum slice is a measuring reference point;

a lens, said-lens located above said stage stage that is used in measurement of to measure the a thickness of said wafer and said datum slice;

- a gas supplier, said gas supplier supplying a gas used to supply a gas;
- a first gas nozzle, said-first gas nozzle locating located on a side of said datum platen;
- a second gas nozzle, said second gas nozzle locating located on a side of said stage;
- a first tube, said-first tube eonnecting connected with said first gas nozzle and said gas supplier;

a second tube, said second tube eonnecting connected with said second gas nozzle and with said gas supplier, wherein said gas supplier supplied supplies said gas passing that passes through said first tube and said second tube, and exhausted exhausts from said first gas nozzle and said second gas nozzle to form a gas stream;

a transport slot, said transport slot collecting which collects said gas in said gas stream, and using a which uses a channel to exhaust said gas stream; and

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said transport slot by using a third tube.

a gas-extracting apparatus, said gas-extracting apparatus eonnecting being connected with

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- 2. (Currently Amended) The measuring system of the gas stream environment according to claim 1, further comprising a first flow rate regulating valve fixing fixed on said first gas nozzle.
- 3. (Currently Amended) The measuring system of the gas stream environment according to claim 1, further comprising a second flow rate regulating valve fixing fixed on said second gas nozzle.
- 4. (Currently Amended) The measuring system of the gas stream environment according to claim 2, wherein said gas-extracting apparatus comprises a gas-extracting motor.
- 5. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said gas-extracting apparatus comprises a venture Venturi structure.
- 6. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said gas is an inert gas.
- 7. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said gas is nitrogen.

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8. (Canceled)

- 9. (Currently Amended) A measuring system of a gas-stream environment, said measuring system of the gas stream environment comprising:
- a stage, said stage locating located on a transport apparatus and a wafer placing placed on said stage;
- a datum platen, said datum platen locating located on said transport apparatus and on a side of said stage to place for placement of a datum slice, wherein said datum slice is a measuring reference point;
- a lens, said lens locating located above said stage that is used to measure the in a measurement of a thickness of said wafer and said datum slice;
 - a gas supplier, said gas supplier supplying a gas used to supply a gas;
 - a first gas nozzle, said first gas nozzle locating located on a side of said datum platen;
 - a second gas nozzle, said-second gas nozzle locating-located on a side of said stage;
- a first tube, said-first tube connecting connected with said first gas nozzle and with said gas supplier;
- a second tube, said-second tube connecting connected with said second gas nozzle and with said gas supplier, wherein said gas supplier supplied said gas passing that passes through said first tube and said second tube, and exhausted exhausts from said first gas nozzle and said second gas nozzle to form a gas stream;
 - a transport slot, said transport slot extracting which extracts said gas; and

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a gas-extracting apparatus, said gas-extracting apparatus connecting being connected with said transport slot by using a third tube.

- 10. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said first tube comprises a first flow rate regulating valve.
- 11. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said second tube comprises a second flow rate regulating valve.
- 12. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said gas-extracting apparatus comprises a gas-extracting motor.
- 13. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said gas-extracting apparatus comprises a venture-Venturi structure.
- 14. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said gas is an inert gas.
- 15. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said gas is a nitrogen.

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16. (Canceled)

17. (Currently Amended) A measuring system of a gas-stream environment, said measuring system comprising:

a stage, said stage locating located on a transport apparatus and a wafer placing placed on said stage;

a datum platen, said datum platen <u>locating located</u> on said transport apparatus and on a side of said stage to place for placement of a datum slice;

a lens, said lens locating located above said stage that is used in a measurement of to measure the a thickness of said wafer and said datum slice;

a gas supplier, said gas supplier supplying a gas used to supply a gas;

a first gas nozzle, said-first gas nozzle locating located on a side of said datum platen and on said transport apparatus to exhaust said gas;

a second gas nozzle, said-second gas nozzle <u>locating-located</u> on a side of said stage and on said transport apparatus to exhaust said gas in said gas stream;

a first tube, said-first tube having a first flow rate regulating valve, and eonnecting connected with said first gas nozzle and with said gas supplier;

a second tube, said second tube having a second flow rate regulating valve and eonnecting connected with said second gas nozzle and with said gas suppler;

a transport slot, said-transport slot is comprising an opening to exhaust said gas; and a gas-extracting apparatus, said gas-extracting apparatus connected with said transport slot by using a third tube and producing an attraction to remove said gas.

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18. (Currently Amended) The measuring system of the gas stream environment according to claim 17, wherein said gas-extracting apparatus comprises a venture Venturi structure.

- 19. (Currently Amended) The measuring system of the gas stream environment according to claim 17, wherein said gas in an inert.
- 20. (Currently Amended) The measuring system of the gas stream environment measuring system accordingly to claim 17, wherein said gas is nitrogen.
- 21. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said first gas nozzle used to exhaust a gas in a gas stream.
- 22. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said transport slot is used to collect said gas in said gas stream.
- 23. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said transport slot <u>is</u> used to <u>be as</u> a channel to exhaust said gas in said gas stream.

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24. (Currently Amended) The measuring system of the gas stream environment according to claim 1, wherein said lens to measure said thickness of said wafer comprises further comprising:

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means for placing said wafer on said stage;

wherein said stage is moved to a place under said lens using said transport apparatus by using a robot; and

moving said stage to the place under said lens by using said transport device;

means for irradiating a light from said lens to a surface of said wafer and the data datum slice,

wherein said data returned from said irradiation is returned from said light and showed shown on a monitor; and

wherein analyzing said data is analyzed to obtain said thickness of said wafer.

25. (Currently Amended) The measuring system of the gas stream environment according to claim 9, wherein said lens to measure said thickness of said wafer comprises further comprising:

means for placing said wafer on said stage by using a robot;

wherein said stage is moved to a place under said lens moving said stage to the place under said lens by using said transport-device apparatus; and

means for irradiating a light from said lens to a surface of said wafer and the data datum slice,

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wherein said data returned from said irradiation is returned from said light and showed shown on a monitor; and

wherein analyzing said data is analyzed to obtain said thickness of said wafer.

26. (Currently Amended) The measuring system of the gas stream environment according to claim 17, wherein said lens to measure said thickness of said wafer comprises further comprising:

means for placing said wafer on said stage by using a robot;

moving said stage to the place under said lens by using said transport device;

wherein said stage is moved to a place under said lens using said transport apparatus; and

means for irradiating a light from said lens to a surface of said wafer and the data datum

wherein said data returned from said irradiation is returned from said light and showed shown on a monitor; and

slice,

wherein analyzing said data is analyzed to obtain said thickness of said wafer.